E Series Power MOSFET

TO-220AB

D

G

S
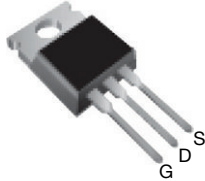
N-Channel MOSFET

FEATURES
- 4th generation E series technology
- Low figure-of-merit (FOM) R_{on} x Q_g
- Low effective capacitance ($C_{o(er)}$)
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

RoHS COMPLIANT

HALOGEN FREE

APPLICATIONS
- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

PRODUCT SUMMARY

V_{DS} (V) at T_J max.		700
$R_{DS(on)}$ typ. (Ω) at 25 °C	V_{GS} = 10 V	0.208
Q_g max. (nC)		29
Q_{gs} (nC)		8
Q_{gd} (nC)		7
Configuration		Single

ORDERING INFORMATION

Package	TO-220AB
Lead (Pb)-free and halogen-free	SiHP240N65E-GE3

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	650	V
Gate-source voltage			V_{GS}	± 30	
Continuous drain current (T_J = 150 °C)	V_{GS} at 10 V	T_C = 25 °C	I_D	16	A
		T_C = 100 °C		10	
Pulsed drain current [a]			I_{DM}	33	
Linear derating factor				1.2	W/°C
Single pulse avalanche energy [b]			E_{AS}	36	mJ
Maximum power dissipation			P_D	147	W
Operating junction and storage temperature range			T_J, T_{stg}	-55 to +150	°C
Drain-source voltage slope			dv/dt	100	V/ns
Reverse diode dv/dt [c]				20	

Notes
a. Repetitive rating; pulse width limited by maximum junction temperature
b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω, I_{AS} = 1.6 A
c. $I_{SD} \leq I_D$, di/dt = 100 A/μs, starting T_J = 25 °C

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R_{thJA}	-	62	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	0.6	

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA		650	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA		-	0.65	-	V/°C
Gate-source threshold voltage (N)	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA		3.0	-	5.0	V
Gate-source leakage	I_{GSS}	V_{GS} = ± 20 V		-	-	± 100	nA
		V_{GS} = ± 30 V		-	-	± 1	µA
Zero gate voltage drain current	I_{DSS}	V_{DS} = 650 V, V_{GS} = 0 V		-	-	1	µA
		V_{DS} = 520 V, V_{GS} = 0 V, T_J = 125 °C		-	-	10	
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS} = 10 V	I_D = 7 A	-	0.208	0.240	Ω
Forward transconductance [a]	g_{fs}	V_{DS} = 20 V, I_D = 7 A		-	1	-	S
Dynamic							
Input capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 100 V, f = 100 kHz		-	960	-	pF
Output capacitance	C_{oss}			-	40	-	
Reverse transfer capacitance	C_{rss}			-	2	-	
Effective output capacitance, energy related [a]	$C_{o(er)}$	V_{DS} = 0 V to 400 V, V_{GS} = 0 V		-	42	-	
Effective output capacitance, time related [b]	$C_{o(tr)}$			-	273	-	
Total gate charge	Q_g	V_{GS} = 10 V	I_D = 7 A, V_{DS} = 520 V	-	19	29	nC
Gate-source charge	Q_{gs}			-	8	-	
Gate-drain charge	Q_{gd}			-	7	-	
Turn-on delay time	$t_{d(on)}$	V_{DD} = 520 V, I_D = 7 A, V_{GS} = 10 V, R_g = 9.1 Ω		-	16	32	ns
Rise time	t_r			-	20	40	
Turn-off delay time	$t_{d(off)}$			-	25	50	
Fall time	t_f			-	12	24	
Gate input resistance	R_g	f = 1 MHz, Open Drain		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristics							
Continuous source-drain diode current	I_S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	16	A
Pulsed diode forward current	I_{SM}			-	-	33	
Diode forward voltage	V_{SD}	T_J = 25 °C, I_S = 7 A, V_{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t_{rr}	T_J = 25 °C, I_F = I_S = 7 A, di/dt = 100 A/µs, V_R = 25 V		-	269	538	ns
Reverse recovery charge	Q_{rr}			-	2.7	5.4	µC
Reverse recovery current	I_{RRM}			-	17	-	A

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 2 - Typical Output Characteristics
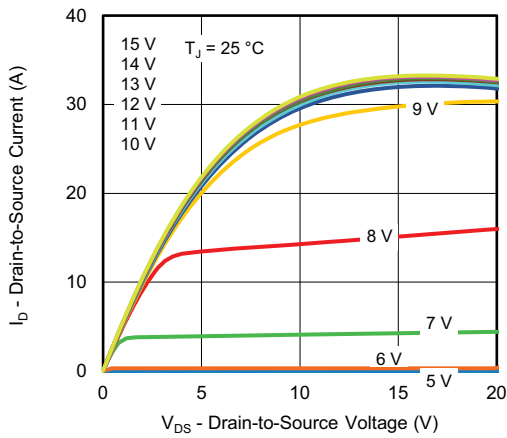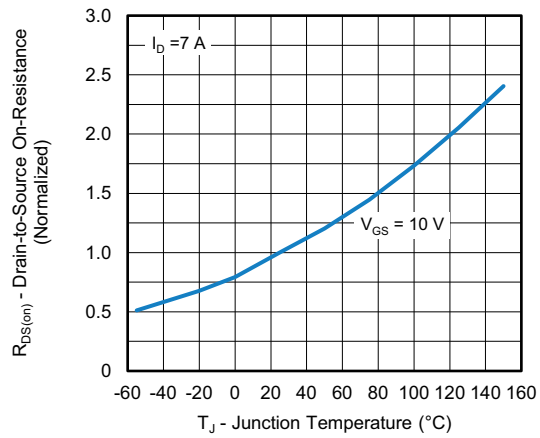

Fig. 3 - Typical Transfer Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature
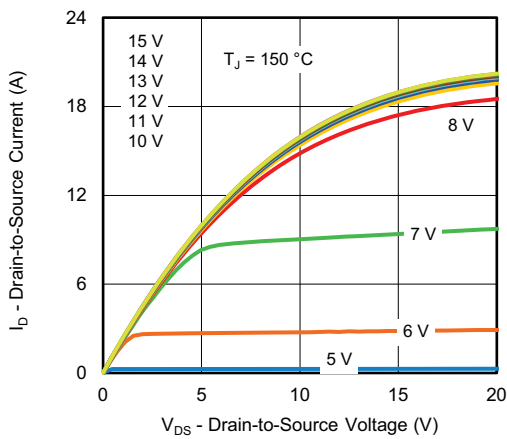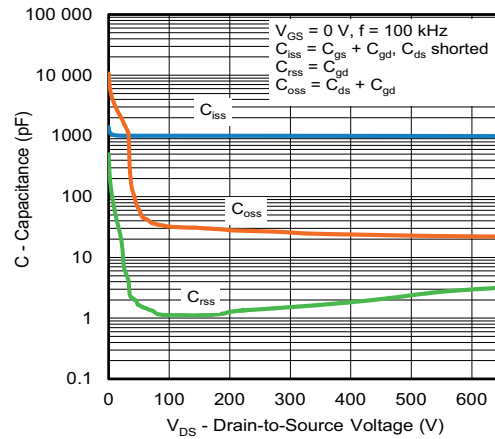
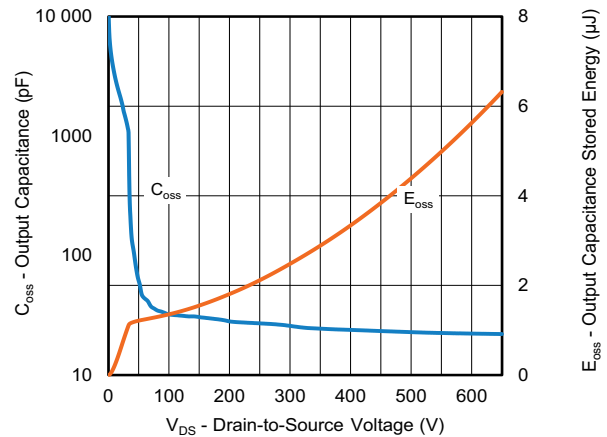Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}
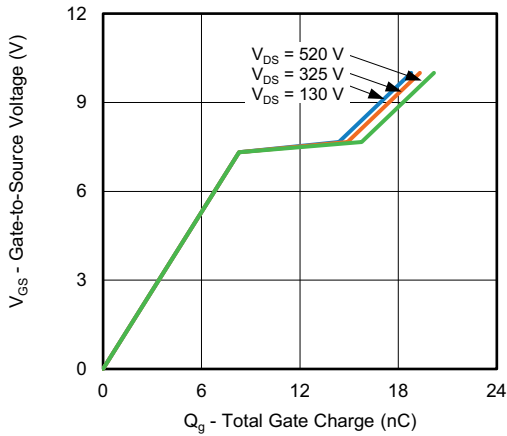
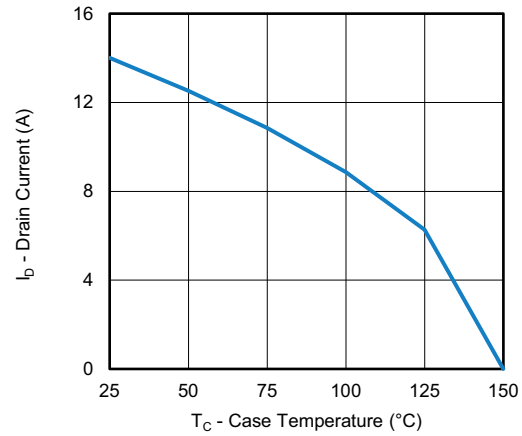**Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage**

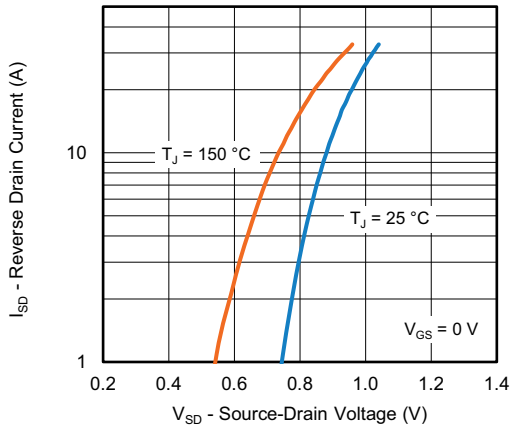**Fig. 10 - Maximum Drain Current vs. Case Temperature**
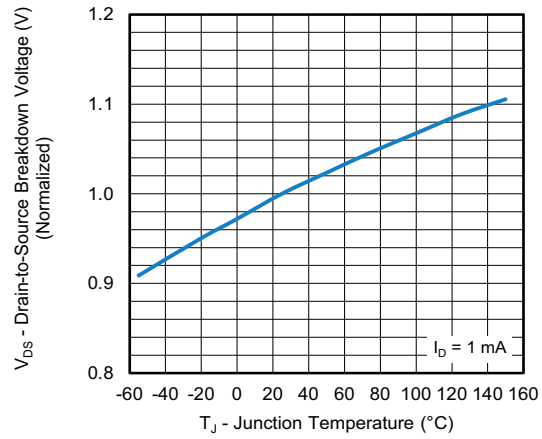

Fig. 8 - Typical Source-Drain Diode Forward Voltage
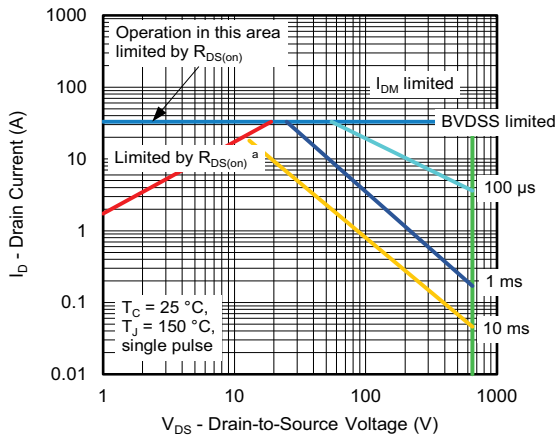

Fig. 11 - Temperature vs. Drain-to-Source Voltage

Fig. 9 - Maximum Safe Operating Area

Note

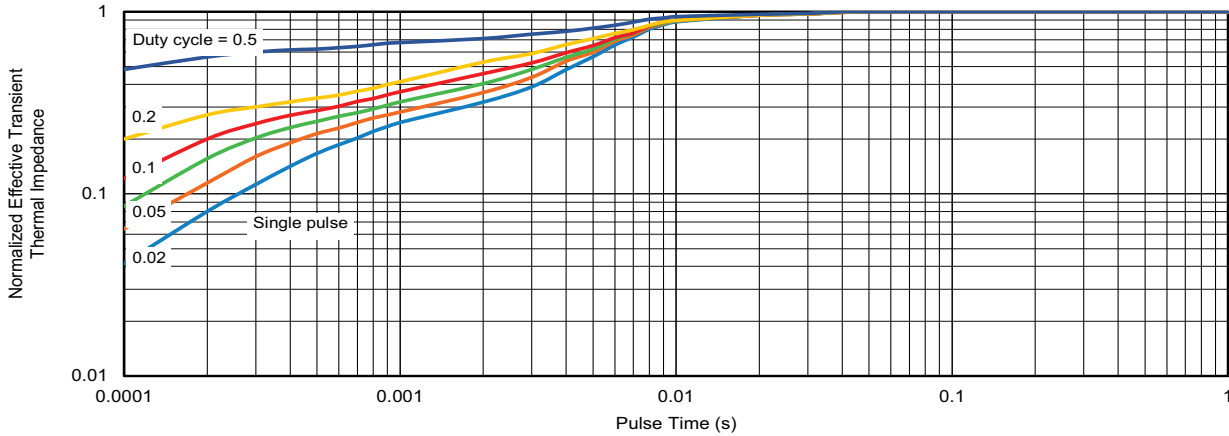a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case
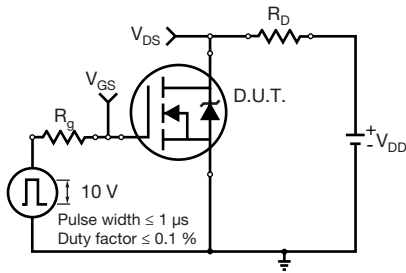

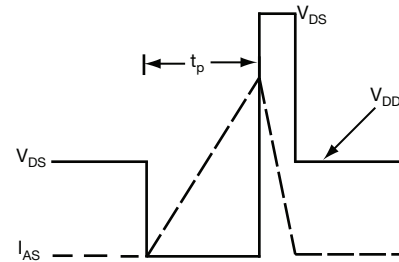**Fig. 13 - Switching Time Test Circuit**

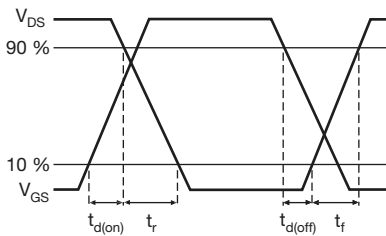**Fig. 16 - Unclamped Inductive Waveforms**

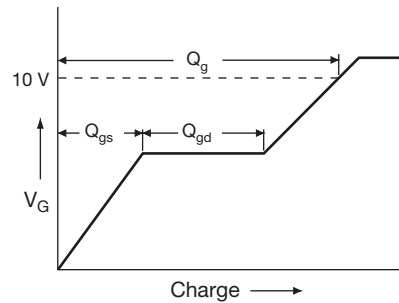**Fig. 14 - Switching Time Waveforms**

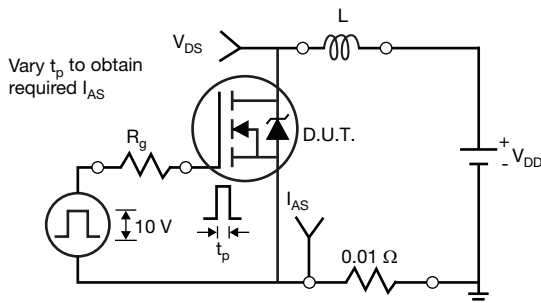**Fig. 17 - Basic Gate Charge Waveform**

Fig. 15 - Unclamped Inductive Test Circuit
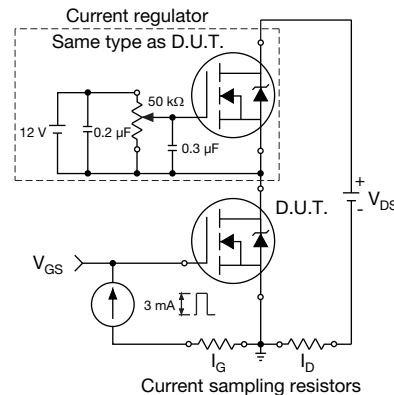
Fig. 18 - Gate Charge Test Circuit
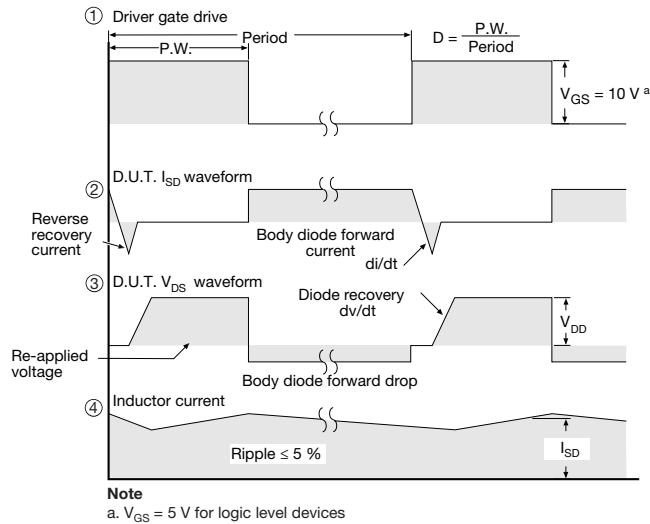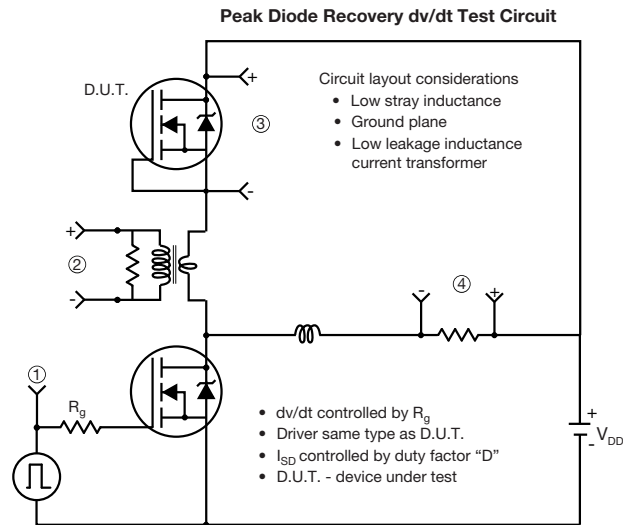
Peak Diode Recovery dv/dt Test Circuit

Circuit layout considerations
- Low stray inductance
- Ground plane
- Low leakage inductance current transformer

- dv/dt controlled by R_g
- Driver same type as D.U.T.
- I_{SD} controlled by duty factor "D"
- D.U.T. - device under test

① Driver gate drive

$$D = \frac{P.W.}{Period}$$

$V_{GS} = 10$ V [a]

② D.U.T. I_{SD} waveform

Reverse recovery current

Body diode forward current

di/dt

③ D.U.T. V_{DS} waveform

Diode recovery dv/dt

V_{DD}

Re-applied voltage

Body diode forward drop

④ Inductor current

Ripple ≤ 5 %

I_{SD}

Note
a. $V_{GS} = 5$ V for logic level devices

Fig. 19 - For N-Channel

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